

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit package including an optical sensor array is provided with a transparent window comprising a thermoset plastic, such as an epoxy transfer clear molding compound, that is resistant to the elevated temperatures found in semiconduc-
tor processing and is configured as a lens, to improve the image quality of the image in-
cident on the sensor. As an example, a field flattener lens is incorporated into the win-
dow to form an integral element that also acts as an hermetic seal. Thus, the field flat-
tener is made integral with the sensor. The thermoset lens provides two functions: (1) it
10 improves the image quality; and (2) it protects the sensor from damage and contamina-
tion. This protection is normally provided by a glass window on the sensor, but is no
longer necessary by virtue of the present invention.

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